

Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit	Conditions
Peak Pulse Power Dissipation	P _{PP}	200	W	8/20µs, Per Figure 3
Peak Pulse Current	I _{PP}	4	Α	8/20µs, Per Figure 3
ESD Protection – Contact Discharge	V _{ESD_Contact}	±30	kV	Standard IEC 61000-4-2
ESD Protection – Air Discharge	V_{ESD_Air}	±30	kV	Standard IEC 61000-4-2
ESD Protection – Human Body Model	V_{ESD_HBM}	±16	kV	MIL-STD-883
Electrical Fast Transient Current	I _{EFT}	80	Α	Standard IEC 61000-4-4(EFT)

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Package Power Dissipation (Note 5)	P _D	300	mW
Thermal Resistance, Junction to Ambient (Note 5)	$R_{\theta JA}$	417	°C/W
Operating Junction Temperature Range	TJ	-65 to +150	°C
Storage Temperature Range	T _{STG}	-65 to +150	°C

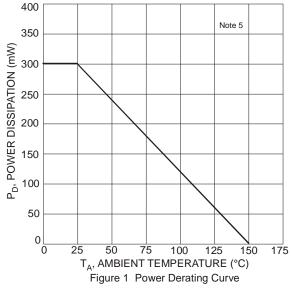
Electrical Characteristics (@TA = +25°C, unless otherwise specified.)

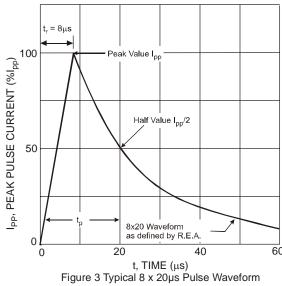
Characteristic	Symbol	Min	Тур	Max	Unit	Test Conditions
Reverse Working Voltage	V_{RWM}	_	_	32	V	_
Breakdown Voltage	V_{BR}	34	_	40	V	I _R = 1.0mA
Reverse Leakage Current (Note 6)	I _R	_	_	100	nA	$V_{RWM} = 32V$
Clamping Voltage (Note 7)	VcL	_	_	42	V	$I_{PP} = 1A, t_p = 8/20\mu s$
		_	_	50	V	$I_{PP} = 4A, t_p = 8/20\mu s$
Channel Input Capacitance	Ст	_	36	42	pF	$V_{IN} = 0V$, $f = 1MHz$, Pin 1 or Pin 2 to Pin 3
		_	18	21	pF	V _{IN} = 0V, f = 1MHz, between Pin 1 and Pin 2

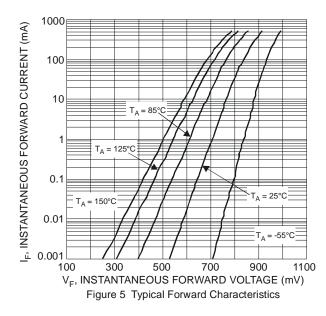
Notes:

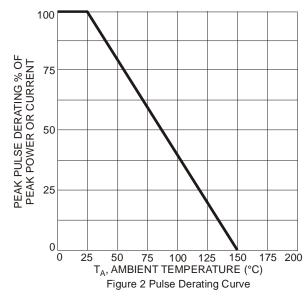
- Device mounted on FR-4 PCB pad layout (2oz copper) as shown on Diodes' website at http://www.diodes.com/package-outlines.html.
 Short duration pulse test used to minimize self-heating effect.
 Measured from pin 1 or pin 2 to pin 3; Non-repetitive current pulse per Figure 3.











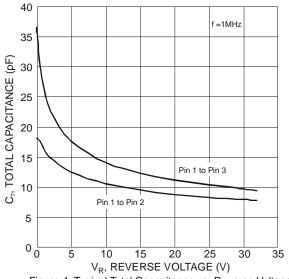


Figure 4 Typical Total Capacitance vs. Reverse Voltage

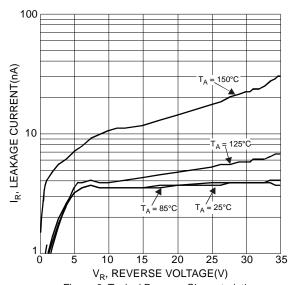


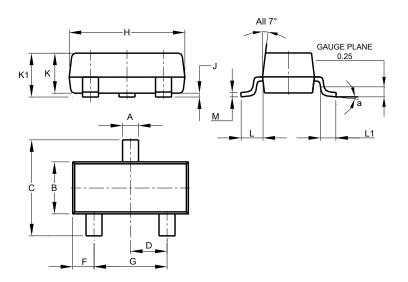
Figure 6 Typical Reverse Characteristics



Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

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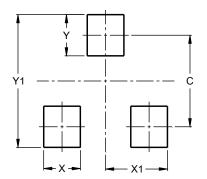


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Dim	Min	Max	Тур		
Α	0.37	0.51	0.40		
В	1.20	1.40	1.30		
C	2.30	2.50	2.40		
D	0.89	1.03	0.915		
F	0.45	0.60	0.535		
G	1.78	2.05	1.83		
Н	2.80	3.00	2.90		
7	0.013	0.10	0.05		
K	0.890	1.00	0.975		
K 1	0.903	1.10	1.025		
L	0.45	0.61	0.55		
L1	0.25	0.55	0.40		
М	0.085	0.150	0.110		
а	0°	8°			
All Dimensions in mm					

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

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Dimensions	Value (in mm)
С	2.0
Х	0.8
X1	1.35
Y	0.9
Y1	29



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